

1. Notes of IC storage

- (1) Do not store the devices in a corrosive-gas atmosphere.
- (2) Do not store the devices in a dusty place.
- (3) Do not expose the devices to direct rays of the sun.
- (4) Do not allow external forces or loads to be applied to ICs.

2. Storage duration

Within a year after delivering this device.

For the products stored longer than a year, confirm their leads and solderability before they are used.

3. IC Storage Conditions for Normal Packing

(1) Temperature and humidity ranges.

Temperature: 5 to 40 (°C)

Humidity : 30 to 75 (%)

The package product does not have a quality problem such as package crack because of humidity absorbing.

The above conditions are recommended for storage. Avoid a dry environment below 30% because the products are easily damageable by the electrical discharge.

Store the products in the place where it does not create dew with the products due to a sudden change in temperature.

※Baking is unnecessary in the above mentioned storage conditions.

(2) Moisture Sensitivity Levels

JEDEC: Level 1

4. IC Storage Conditions for Moisture-Proof Packing

(1) Temperature and humidity ranges.

Pack Sealing Temperature: 5 to 40 [°C]

Humidity : 40 to 80 [%]

Pack Opening Temperature: 5 to 40 [°C]

Humidity : 40 to 60 [%]

Use product within a month after opening the package.

Avoid a dry environment below 40% because the product is easily destructed by the electrical discharge.

Store the products in the place where it does not create dew with the products due to a sudden change in temperature.

※Do not put the package in a baking process because the package is not heatproof specification.

(2) Moisture Sensitivity Level

JEDEC: Level 2a

5. IC Storage Conditions for Deaeration Packing

(1) Temperature and humidity ranges.

Before the break of the anti-humidity seal Temperature: 5 to 40 (°C)

Humidity : Within 80 (%)

After the break of the anti-humidity seal Temperature: 5 to 25 (°C)

Humidity : 40 to 60 (%)

Be sure to use within 7days After the break of the anti-humidity seal and to apply 2nd soldering within 3days.

The above conditions are recommended for storage. Avoid a dry environment below 40% because the products are easily damageable by the electrical discharge.

Store the products in the place where it does not create dew with the products due to a sudden change in temperature.

(2) Baking

In case of keeping except above condition, be sure to apply baking. (Heat proof tray)

Baking Method: Ta=125°C, over 16h

(3) Moisture Sensitivity Level

JEDEC: Level 3

1. CLEANING CONDITIONS

When Cleaning is needed the following conditions are recommended as the ultrasonic cleaning:

Frequency: 28kHz
Power: 20W/□
Temperature: 40°C
Time: 30 to 60s

- (Note1) Do not brush ink marks while cleaning because the marks will be wipe out.
(Note2) Do not resonate the products.
(Note3) Do not let the products or their mounted board come into contact with the vibrator.

2. CLEANING CONDITIONS (Opt Electronics)

(1) Please refrain from cleaning of the device as much as possible.

A void the solvent or the vapor solvent from the resin of the device even during the mounting and using.

(2) This device can be cleaned if it is only a lead part when the cleaning of flux etc is indispensable.

However, clean the device by using the following solvent by the condition within 35°C and 3minute.

Solvent : isopropyl alcohol, methyl alcohol

(3) Do not clean the reflow correspondence product immediately after the reflow.